



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-19
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*0158BJ6	A	BO2A	2016-02-19
Amount	UoM	Unit type	ST ECOPACK Grade	
34.885	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.4x3x0.9	8	gull wing	
Comment	Package: 6P TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for LM2904AHYPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6P*0158BJ6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.722	mg	supplier	die	Silicon (Si)	7440-21-3		0.705	mg	976454	20209
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	8310	172
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	4155	86
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	5540	115
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.004	mg	5540	115
Leadframe	Copper & its alloys	13.864	mg	supplier	alloy	Copper (Cu)	7440-50-8		12.537	mg	904284	359381
				supplier	alloy	Nickel (Ni)	7440-02-0		0.391	mg	28203	11208
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.020	mg	1443	573
				supplier	alloy	Silicon (Si)	7440-21-3		0.085	mg	6131	2437
				supplier	metallization	Nickel (Ni)	7440-02-0		0.285	mg	20557	8170
				supplier	metallization	Palladium (Pd)	7440-05-3		0.018	mg	1298	516
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	577	229
				supplier	metallization	Silver (Ag)	7440-22-4		0.520	mg	37507	14906
				supplier	glue	Silver (Ag)	7440-22-4		0.260	mg	878378	7453
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.015	mg	50676	430
Die attach	Other Organic Materials	0.296	mg	supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.015	mg	50676	430
				supplier	glue	Acrylate polymer	87320-05-6		0.006	mg	20270	172
				supplier	wire	Copper (Cu)	7440-50-8		0.065	mg	1000000	1863
				supplier	mold compound	Silica, vitreous	60676-86-0		17.485	mg	876969	501218
Bonding wires	Other inorganic materials	0.065	mg	supplier	mold compound	Epoxy resin	85954-11-6		0.798	mg	40024	22875
				supplier	mold compound	Epoxy	29690-82-2		0.798	mg	40024	22875
				supplier	mold compound	phenol resin	Proprietary		0.598	mg	29993	17142
				supplier	mold compound	additive	Proprietary		0.199	mg	9981	5704
				supplier	mold compound	carbon black	1333-86-4		0.060	mg	3009	1720
Encapsulation	Other Organic Materials	19.938	mg	supplier	mold compound	Epoxy resin	85954-11-6		0.798	mg	40024	22875
				supplier	mold compound	Epoxy	29690-82-2		0.798	mg	40024	22875
				supplier	mold compound	phenol resin	Proprietary		0.598	mg	29993	17142
				supplier	mold compound	additive	Proprietary		0.199	mg	9981	5704
				supplier	mold compound	carbon black	1333-86-4		0.060	mg	3009	1720